

IN THE SPECIFICATION:

Please amend the paragraph found on p. 13, lines 9-12 as follows:

FIG. 5B illustrates a stack 500 of various layers present after the reactive ion etching operation 464 of the method 450 of FIG. 4. As shown, the reactive ion etching creates a trench 510 through the transfer layer 504 and the etch CMP_stop/adhesion layer 506 (if it exists). Such trench 510 terminates at an upper surface of the etch stop layer 502.